US00D401249S

# United States Patent [19]

**Kawakita**

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[54] **ROLLER FOR A WIRE SAW FOR SEMICONDUCTORS**

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[73] Assignee: **Nippei Toyama Corporation**, Tokyo, Japan

[**] Term: **14 Years**

[21] Appl. No.: **75,089**

[22] Filed: **Aug. 12, 1997**

[51] **LOC (6) Cl.** .......................................................... **15-09**

[52] **U.S. Cl.** ........................................... **D15/133**; D15/138

[58] **Field of Search** .................................... D15/133, 138, D15/139; 83/651.1, 171; 125/16.02

[56] **References Cited**

U.S. PATENT DOCUMENTS

| | | | |
|---|---|---|---|
| D. 369,361 | 4/1996 | Satake | D15/138 X |
| 5,715,807 | 2/1998 | Toyama et al. | 125/16.02 |

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*Attorney, Agent, or Firm*—Trask, Britt & Rossa

[57] **CLAIM**

The ornamental design for a roller for a wire saw for semiconductors, as shown and described.

## DESCRIPTION

FIG. **1** is a front elevational view of a roller for a wire saw for semiconductors, the rear elevational view being a mirror image of FIG. **1**;

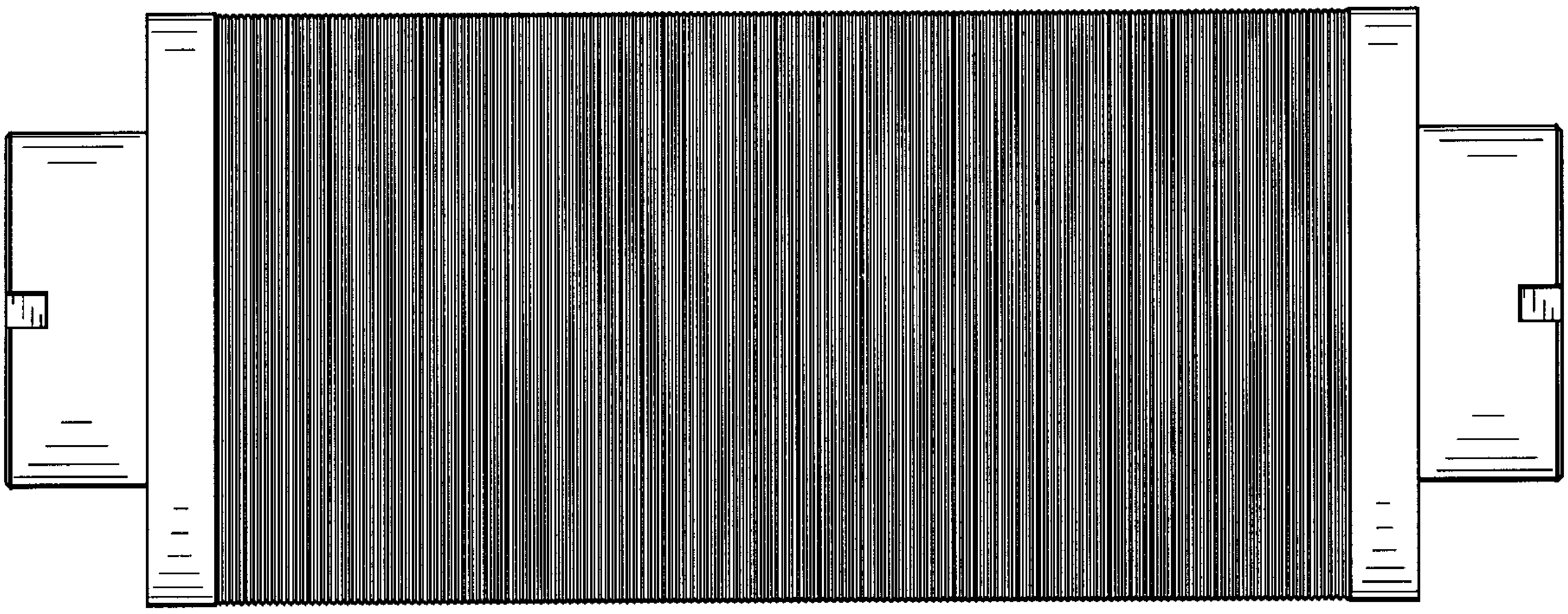
FIG. **2** is a top plan view thereof, the bottom plan view being identical with FIG. **2**;

FIG. **3** is a right side elevational view thereof, the left side elevational view being identical with FIG. **3**;

FIG. **4** is a perspective view thereof; and,

FIG. **5** is a referential view showing location of the present article in a wire saw for semiconductors.

**1 Claim, 5 Drawing Sheets**



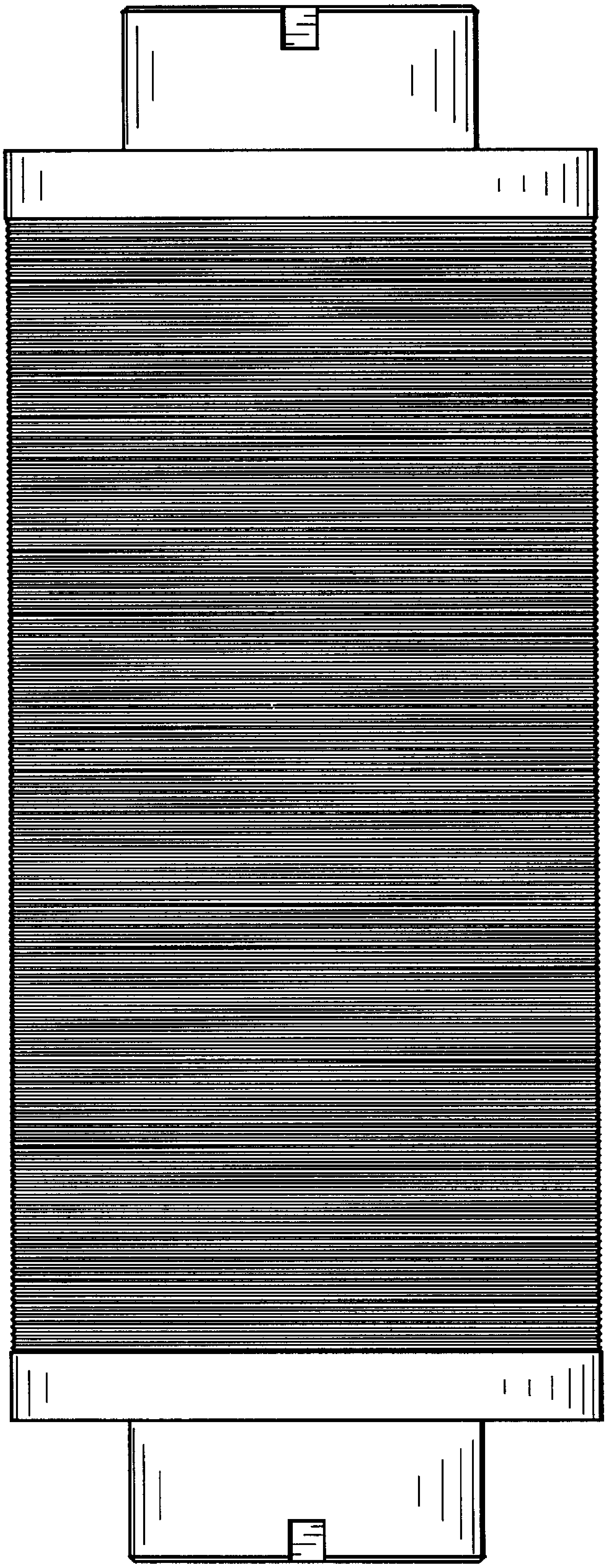


*Fig. 1*

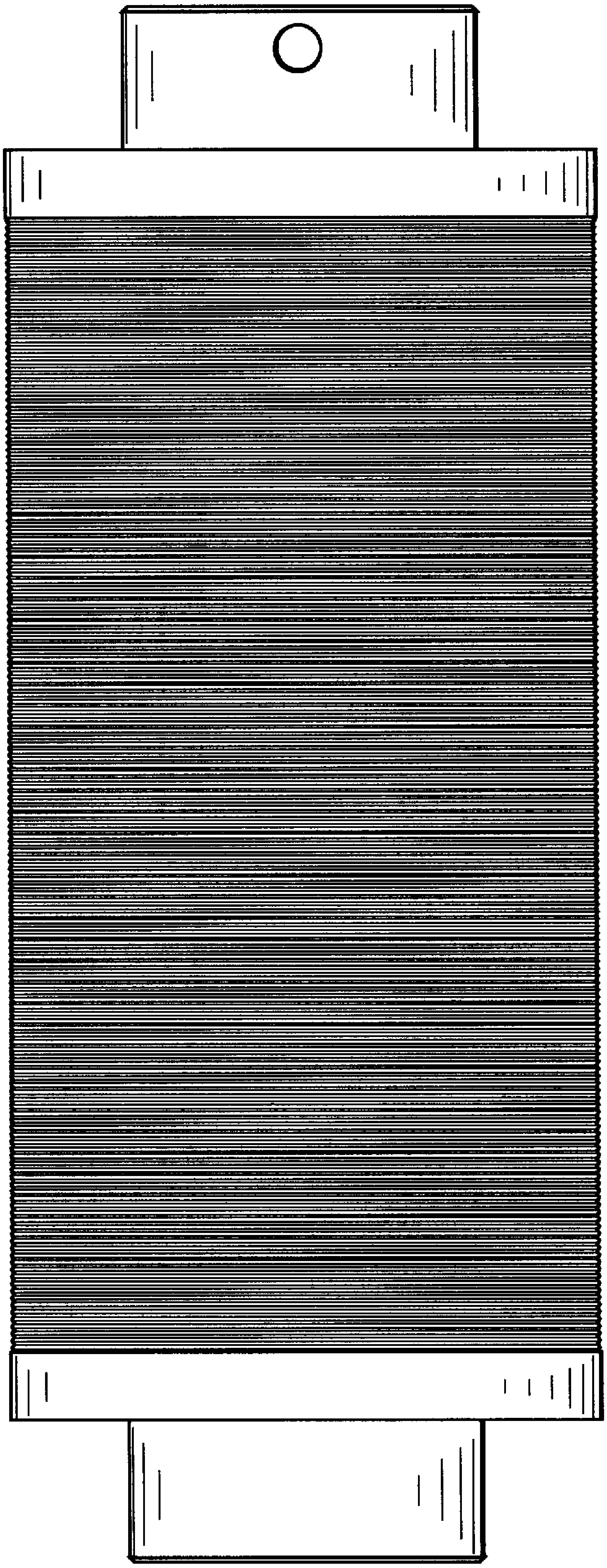
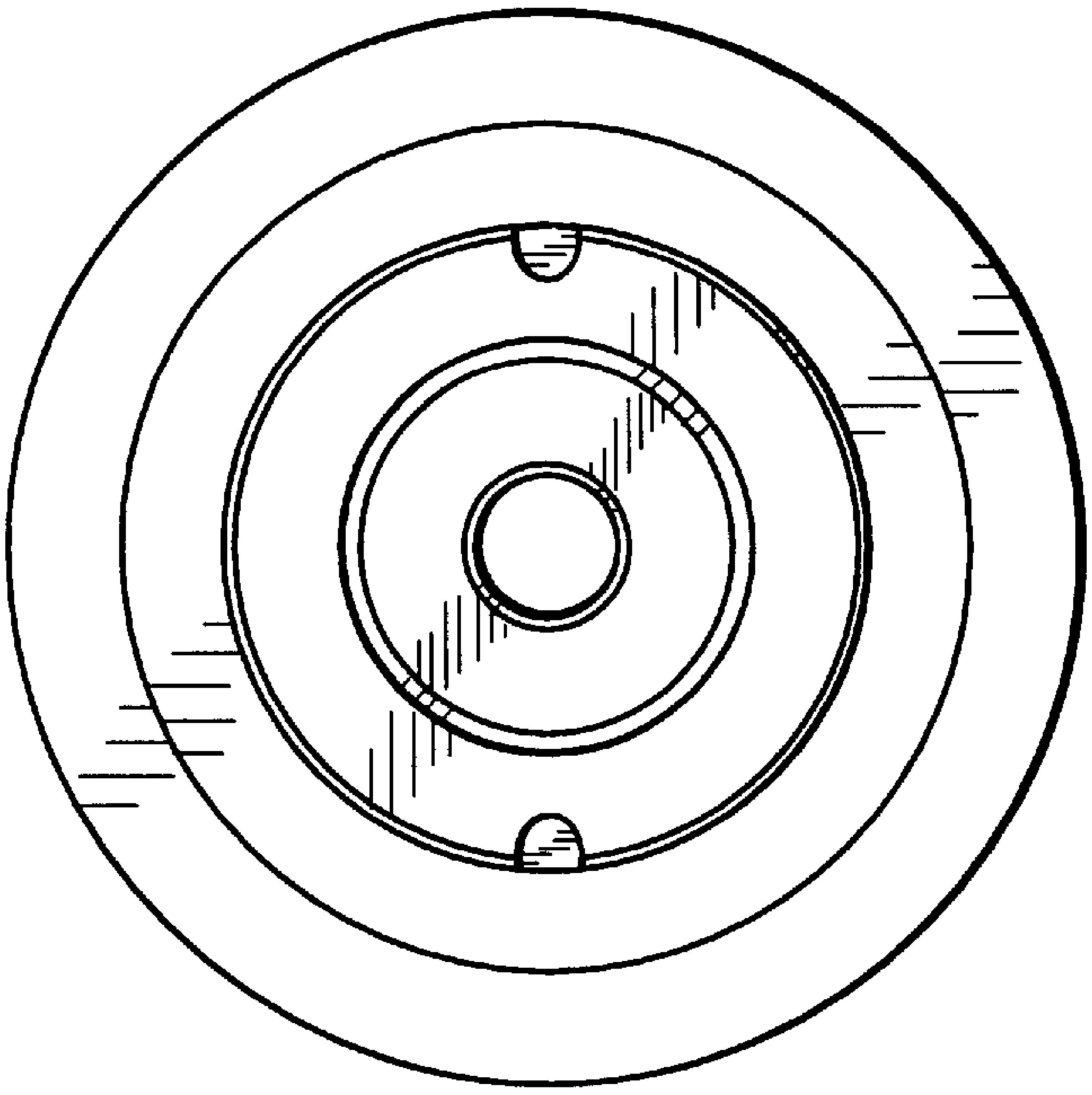


Fig. 2

*Fig. 3*



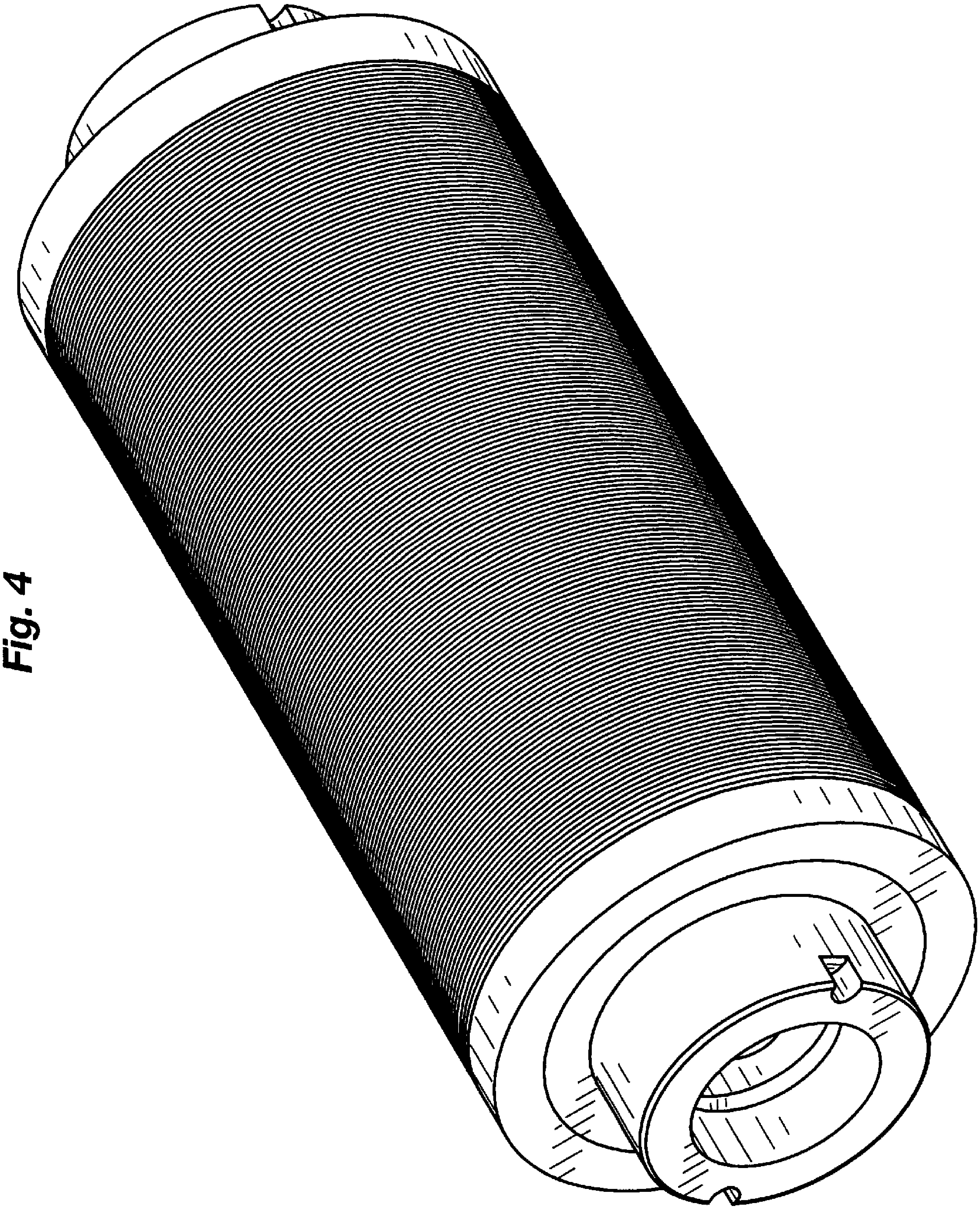


Fig. 4

Fig. 5